

HVB14S

Silicon Epitaxial Planar PIN Diode for High Frequency Attenuator

HITACHI

ADE-208-484A (Z)

Rev.1
May 2001

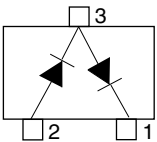
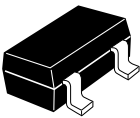
Features

- Low forward resistance. ($r_f = 7.0 \Omega$ max)
- Low capacitance. ($C = 0.25$ pF typ)
- CMPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code
HVB14S	H6	CMPAK

Pin Arrangement



(Top View)

1. Cathode
2. Anode
3. Cathode
Anode

Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	V_R	50	V
Forward current	I_F	50	mA
Power dissipation	P_d^{*1}	100	mW
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	-55 to +125	°C

Note: 1. Two device total.

Electrical Characteristics ^{*1}

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward Vooltage	V_F	—	—	1.0	V	$I_F = 50\text{ mA}$
Reverse current	I_R	—	—	100	nA	$V_R = 50\text{ V}$
Capacitance	C	—	0.25	—	pF	$V_R = 50\text{ V}$, $f = 1\text{ MHz}$
Forward resistance	r_f	—	—	7	Ω	$I_F = 10\text{ mA}$, $f = 100\text{ MHz}$
ESD-Capability ^{*2}	—	200	—	—	V	$C = 200\text{ pF}$, Both forward and reverse direction 1 pulse

Notes: 1. Per one device.

2. Failure criterion ; $I_R \geq 200\text{ nA}$ at $V_R = 50\text{ V}$

Main Characteristic

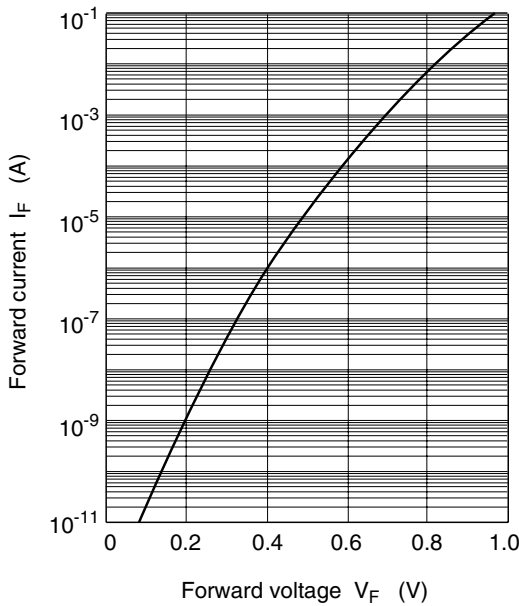


Fig.1 Forward current vs. Forward voltage

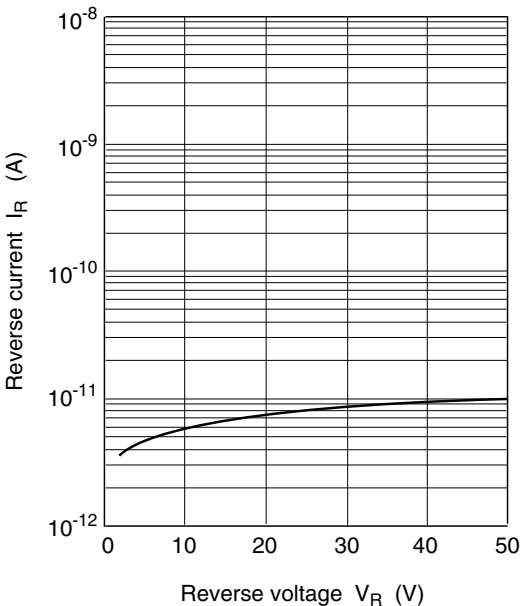


Fig.2 Reverse current vs. Reverse voltage

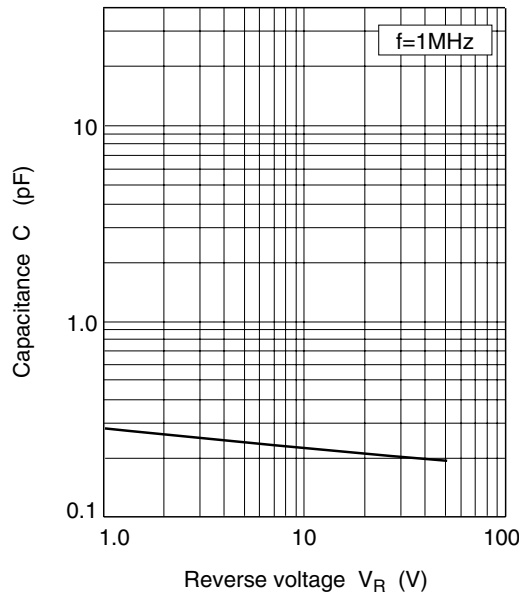


Fig.3 Capacitance vs. Reverse voltage

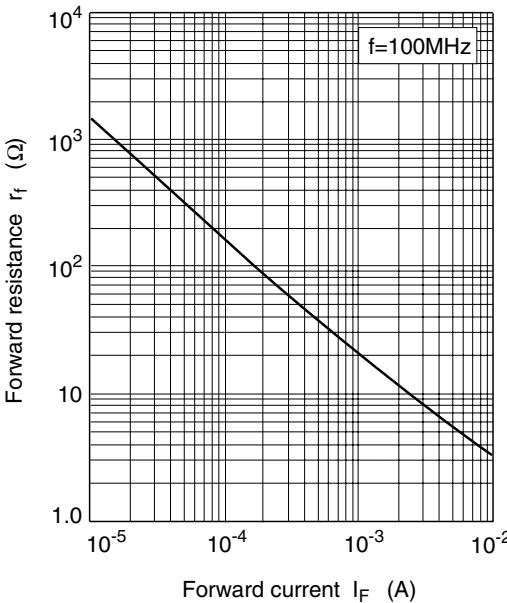
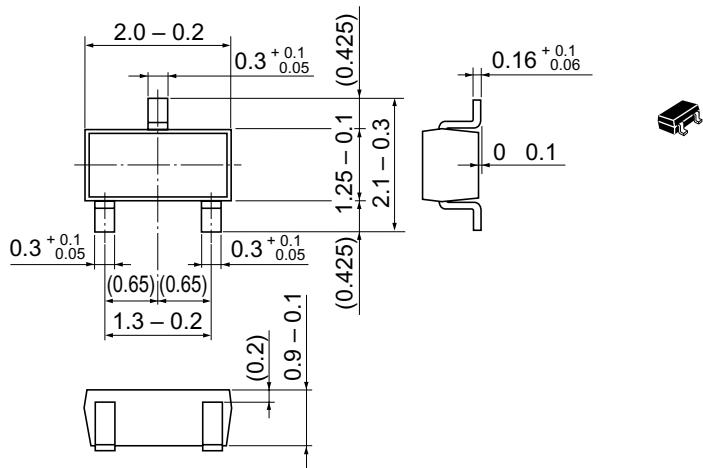


Fig.4 Forward resistance vs. Forward current

Package Dimensions

As of January, 2001
Unit: mm



Hitachi Code	CMPAK
JEDEC	
EIAJ	Conforms
Mass (reference value)	0.006 g

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